FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
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20 May 2009

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16270

TITLE: Transfer of wafer thinning or Backgrind activity from Semigrind to Corwil

PROPOSED FIRST SHIP DATE: 10 Aug 2009

AFFECTED CHANGE CATEGORY(S): Wafer Processing

AFFECTED PRODUCT DIVISION(S): DMSG BU

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Thelma Hammer <Thelma.Hammer@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Not Available
Contact your local ON Semiconductor Sales Office or Daniel Vanderstraeten <Daniel.Vanderstraeten@onsemi.com >

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

ON Semi is consolidating the wafer thinning or Backgrind activity in the US at our preferred subcon, Corwil Technology, Inc.

Corwil is already being used for wafer thinning of ON Semi products. However, an additional qualification was also performed to gather data required to allow transfer of products from other subcons. Corwil passed the backgrind qualification.

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Backgrind Qual Result :

- 8” Wafers ground to 22 mils with a 2000 grit finish
- 5” Wafers ground to 11 mils with a 2000 grit finish
- PDMS free B/G tape used for all wafers
- No rejectable visual defects detected at any of the B/G process steps for all wafers
- All wafers inspected to ON Semi 08-0336 die visual inspection criteria
- Total thickness variation is below the maximum of 10 um for all wafers
- Wafer roughness for measured 8” and 5” wafers all below 0.30 um

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RELIABILITY DATA SUMMARY: Not Applicable

ELECTRICAL CHARACTERISTIC SUMMARY: Not Applicable

CHANGED PART IDENTIFICATION: Not Applicable

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AFFECTED DEVICE LIST

19507-003-XWF
14175-002-XWF
19179-001-XWF
19507-001-XWF
19113-001-XWF
14175-004-XWF
14206-002-XWF
14206-004-XWF
14237-001-XWF
11588-001-XWF
14074-003-XWF
14074-002-XWF
13954-003-XWF
13954-002-XWF
13756-002-XWF
14175-003-XWF
14175-001-XWF
14206-005-XWF
14206-003-XWF
14206-001-XWF
19507-002-XWF